

Appl. No. 10/064,462
Amdt. dated March 30, 2005
Reply to Office action of December 01, 2004

AMENDMENTS TO THE CLAIMS

1. (currently amended) A method for attaching ~~[[a]]~~ an
integrated circuit (IC) package to a circuit board, the
5 IC package having a plurality of electrical contacts,
the plurality of electrical contacts being disposed on
a major surface of the IC package in an arrangement having
a perimeter, the method comprising:

10 positioning the IC package relative to the circuit
board, such that the major surface of the IC
package is adjacent to a major surface of the
circuit board;

15 electrically connecting the IC package to the
circuit board through the plurality of
electrical contacts; and
attaching disposing at least one ~~anchor~~ metal strap
directly to the IC package to mechanically
attaching attach the IC package to the circuit
board;

20 wherein the ~~anchor~~ metal strap does not provide an
electrical contact between the IC package and the
circuit board.

25 2. (currently amended) The method of claim 1 wherein the
~~anchor~~ metal strap is disposed at a location outside of
the perimeter of the plurality of electrical contacts.

3. (original) The method of claim 2 wherein the major

Appl. No. 10/064,462
Amdt. dated March 30, 2005
Reply to Office action of December 01, 2004

surface of the IC package has a rectangular shape, and the arrangement of the plurality of electrical contacts is a grid-like array.

5 4. (currently amended) The method of claim 3 wherein ~~the anchors~~ metal straps are disposed at four corners of the major [[face]] surface of the IC package.

10 5. (currently amended) The method of claim 3 wherein ~~the anchors~~ metal straps are disposed along four edges of the major [[face]] surface of the IC package.

15 6. (currently amended) The method of claim 3 wherein ~~the anchors~~ metal straps are disposed on edges of the IC package.

7-11. (cancelled)

20 12. (original) The method of claim 1 wherein the electrical contacts are solder balls.

13. (original) The method of claim 1 wherein the electrical contacts are pins.

25 14. (new) A method for attaching an integrated circuit (IC) package to a circuit board, the IC package having a plurality of electrical contacts, the plurality of electrical contacts being disposed on a major surface

Appl. No. 10/064,462
Amdt. dated March 30, 2005
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of the IC package in an arrangement having a perimeter,
the method comprising:

positioning the IC package relative to the circuit
board, such that the major surface of the IC
5 package is adjacent to a major surface of the
circuit board;

electrically connecting the IC package to the
circuit board through the plurality of
electrical contacts; and

10 disposing at least one strip of solder between the
major surface of the IC package and the major
surface of the circuit board to mechanically
attach the IC package to the circuit board;

wherein the strip of solder does not provide an
15 electrical contact between the IC package and the
circuit board.

15. (new) The method of claim 14 wherein the strip of
solder is disposed at a location outside of the perimeter
20 of the plurality of electrical contacts.

16. (new) The method of claim 15 wherein the major surface
of the IC package has a rectangular shape, and the
arrangement of the plurality of electrical contacts is
25 a grid-like array.

17. (new) The method of claim 16 wherein the strip of
solder is disposed along four edges of the major surface

Appl. No. 10/064,462
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of the IC package.